WHAT IS CLAIMED IS:

1. A solder deposition method comprising the steps of:

forming a dam around an electrode on a substrate;

applying a solder precipitating composition to said substrate; and

depositing solder on the surface of said electrode while heating said solder precipitating composition applied.

2. The solder deposition method according to claim 1 wherein said step of forming a dam includes the steps of:

forming a resin film on the surface of said substrate; and

providing an opening part in said resin film so that a dam is formed around an electrode on a substrate.

3. The solder deposition method according to claim 1 wherein said dam is not removed after depositing solder.

4. The solder deposition method according to claim 1 wherein said substrate is a via-on-pad structured substrate.

5. The solder deposition method according to claim 1 wherein said solder precipitating composition contains:

tin powder; and

a complex of at least one selected from silver ions and copper ions, and at least one selected from aryl phosphines, alkyl phosphines and azoles.

6. The solder deposition method according to claim 1 wherein said solder precipitating composition contains tin powder and salt of at least one metal selected from lead, copper and silver.

7. A solder bump forming method comprising the steps of:

forming a dam around an electrode on a substrate;

applying a solder precipitating composition to said substrate; and

forming a solder bump by depositing solder on the surface of said electrode while heating said solder precipitating composition applied.